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Anaren

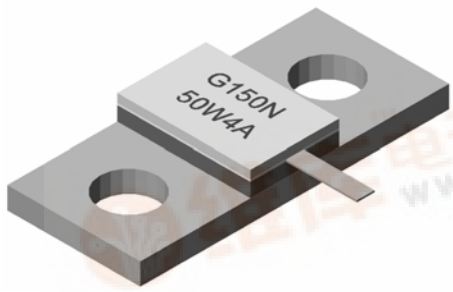
ROHS Compliant

Model G150N50W4A

RF Power

Flange Mount Termination

150 Watts, 50Ω



Description

The G150N50W4A is high performance Aluminum Nitride (AlN) flange mount termination intended as a cost competitive alternative to Beryllium Oxide (BeO). The termination is well suited to all cellular frequency bands such as; AMPS, GSM, DCS, PCS, PHS and UMTS. The high power handling makes the part ideal for terminating circulators, and for use in power combiners. The termination is also RoHS compliant!

Features:

- **RoHS Compliant**
- **150 Watts**
- **DC - 2.7 GHz**
- **AlN Ceramic**
- **Non-Nichrome Resistive Element**
- **Low VSWR**
- **100% Tested**

General Specifications

Resistive Element	Thick Film
Substrate	AlN Ceramic
Cover	Alumina Ceramic
Mounting Flange	Nickel Plated Copper

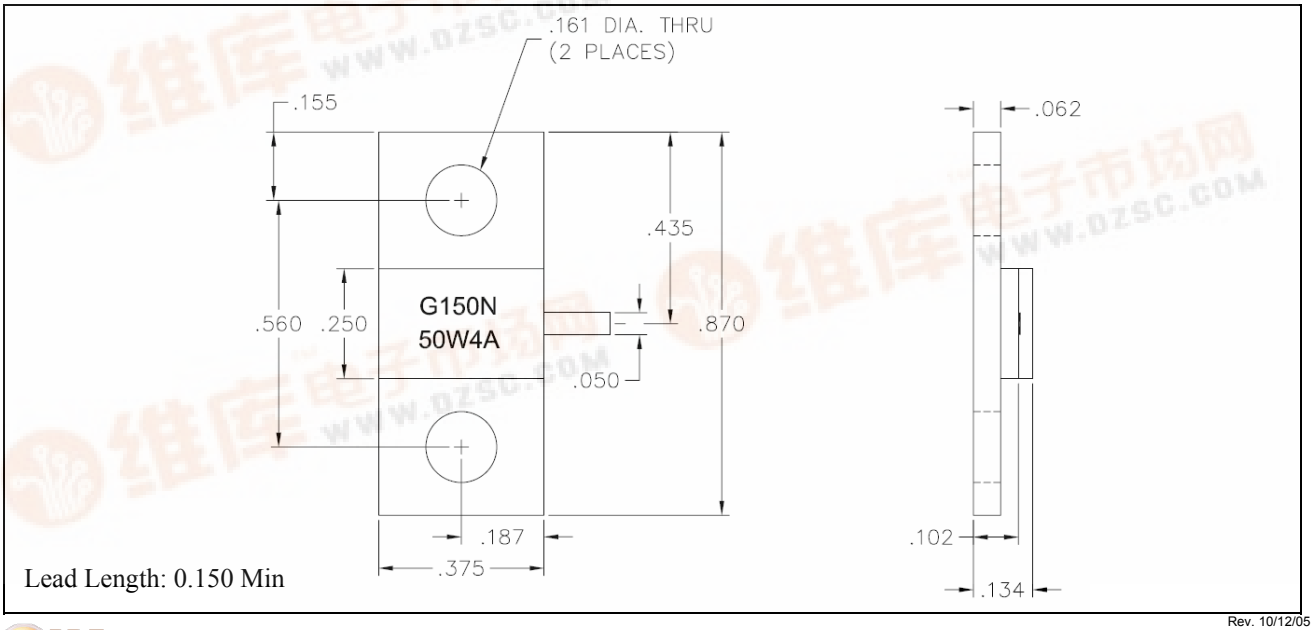
Tolerance is ±0.010", unless otherwise specified. Designed to meet of exceed applicable portions of MIL-E-5400. All dimensions in inches.

Electrical Specifications

Resistance Value:	50 Ohms, ± 2%
Power:	150 Watts
Frequency Range:	DC – 2.7 GHz
Return Loss	>26 dB to 2.0 GHz >17 dB to 2.7 GHz

Specification based on unit properly installed using suggested mounting instructions and a 50 ohm nominal impedance. **Specifications subject to change.**

Outline Drawing



Rev. 10/12/05

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Toll Free: (800) 544-2414

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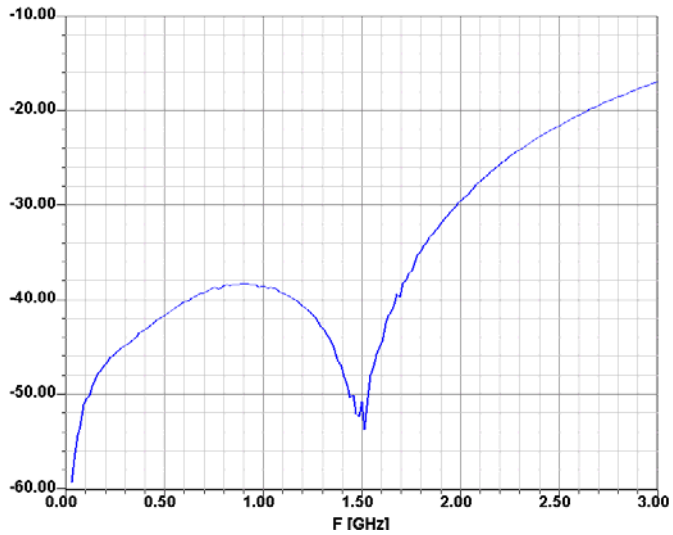
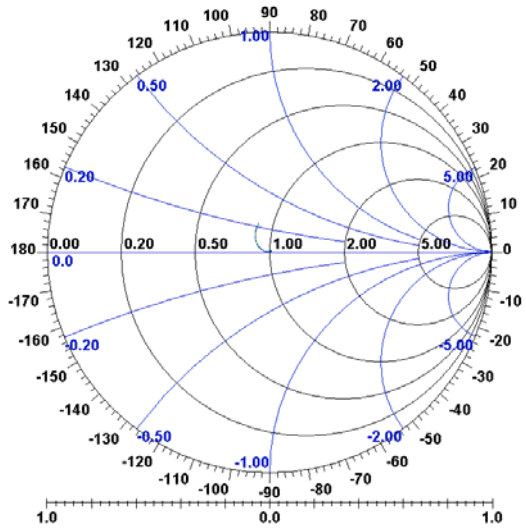
Typical Performance:



G150N50W4A



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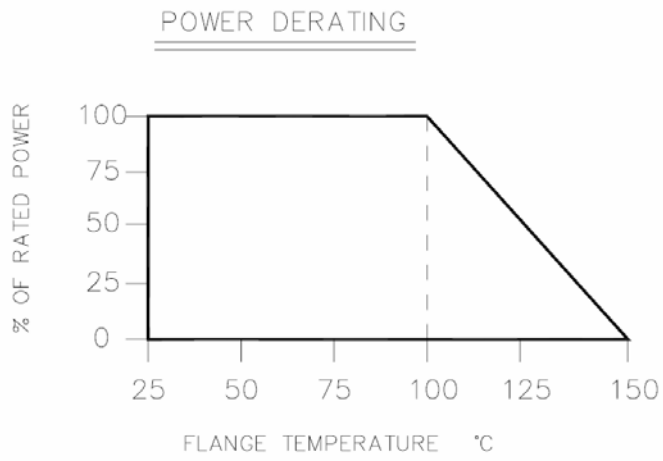
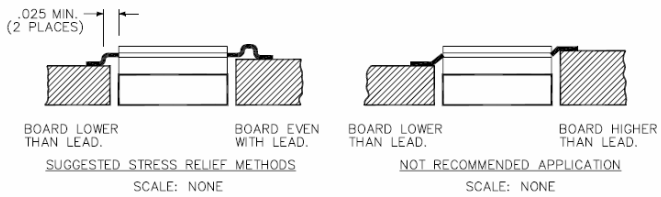
Power De-rating:



Mounting Footprint and Procedure:



SUGGESTED MOUNTING PROCEDURES:

1. MAKE SURE THAT THE DEVICES ARE MOUNTED ON FLAT SURFACES (.001" UNDER THE DEVICE) TO OPTIMIZE THE HEAT TRANSFER.
2. DRILL & TAP THE HEATSINK FOR THE APPROPRIATE THREAD SIZE TO BE USED.
3. COAT HEATSINK WITH A MINIMUM AMOUNT OF HIGH QUALITY SILICONE GREASE (.001" MAX. THICKNESS).
4. POSITION DEVICE ON MOUNTING SURFACE & SECURE USING SOCKET HEAD SCREWS, FLAT & SPLIT WASHER. TORQUE SCREWS TO THE APPROPRIATE VALUE. MAKE SURE THAT THE DEVICE IS FLAT AGAINST THE HEATSINK. (CARE SHOULD BE TAKEN TO AVOID UPWARD PRESSURE OF THE LEADS TOWARDS THE LID).
5. SOLDER LEADS IN PLACE USING LEAD FREE TYPE SOLDER WITH A CONTROLLED TEMPERATURE IRON